

# Power Module Packaging Market

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## Abstracts

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The future of the power module packaging market looks promising with opportunities in the electric vehicle (EV)/hybrid electric vehicle (HEV), motor, rail traction, wind turbine, and solar photovoltaic industries. The global power module packaging market is expected to grow with a CAGR of 9% to 11% from 2020 to 2025. The major growth drivers for this market growth of the electric vehicle and solar PV industries.

A total of XX figures / charts and XX tables are provided in more than 150 pages report is developed to help in your business decisions. Sample figures with some insights are shown below. To learn the scope of, benefits, companies researched and other details of power module packaging market report download the report brochure.

power module packaging

Growth in various segments of the power module packaging market are given below:

power module packaging

The study includes trends and forecast for the global power module packaging market by packaging solution, end use industry, and region as follows:

By Packaging Solution [\$M shipment analysis for 2014 – 2025]:

Die attach Baseplate Substrate Attach Substrate Encapsulation Interconnection Others

By End Use Industry [\$M shipment analysis for 2014 – 2025]:

Electric Vehicles (EV)/Hybrid Electric Vehicles (HEV)MotorsRail TractionWind  
TurbinesSolar Photovoltaic Others

By Region [\$M shipment analysis for 2014 – 2025]:

North AmericaUnited StatesCanadaMexicoEuropeGermanyUKFranceAsia  
PacificChinaJapanIndiaSouth KoreaRest of the World

Some of the power module packaging manufacturers profiled in this report include, Fuji Electric Co. Ltd, Infineon Technologies AG, Mitsubishi Electric Corporation (Powerex Inc.), Amkor Technology Inc., Hitachi Ltd.

Lucintel forecasts that baseplate will remain the largest segment over the forecast period due to the growth of the electric vehicle market.

Within this market, electric vehicle is expected to witness the highest growth over the forecast period due to increasing focus of various countries towards reduction of carbon emissions.

APAC is expected to witness highest growth over the forecast period due to growth of the renewable capacity expansion, which continues to be driven mostly by new installations of solar and wind energy.

### Features of the Global Power Module Packaging Market

Market Size Estimates: Global power module packaging market size estimation in terms of value (\$M) shipment.Trend and Forecast Analysis: Market trend (2014-2019) and forecast (2020-2025) by various segments and regions.Segmentation Analysis: Global power module packaging market size by various segments, such as packaging solution, end use industry, in terms of value.Regional Analysis: Global power module packaging market breakdown by the North America, Europe, Asia Pacific, and Rest of the World.Growth Opportunities: Analysis of growth opportunities in different packaging solution, end use industry, and region for the global power module packaging market.Strategic Analysis: This includes M&A, new product development, and competitive landscape of the global power module packaging market.Analysis of competitive intensity of the industry based on Porter's Five Forces model.

This report answers following key questions

- Q.1 What are some of the most promising potential, high-growth opportunities for the power module packaging market by packaging solutions (die attach, baseplate, substrate attach, substrate, encapsulation, and interconnection, and others), by end use industry (electric vehicles (EV)/hybrid electric vehicles (HEV), motors, rail tractions, wind turbines, solar photovoltaic, and others), and region (North America, Europe, Asia Pacific (APAC), and Rest of the World (ROW))?
- Q. 2 Which segments will grow at a faster pace and why?
- Q.3 Which regions will grow at a faster pace and why?
- Q.4 What are the key factors affecting market dynamics? What are the drivers and challenges of the market?
- Q.5 What are the business risks and threats to the power module packaging market?
- Q.6 What are emerging trends in power module packaging market and the reasons behind them?
- Q.7 What are some changing demands of customers in the power module packaging market?
- Q.8 What are the new developments in the power module packaging market? Which companies are leading these developments?
- Q.9 Who are the major players in this power module packaging market? What strategic initiatives are being implemented by key players for business growth?
- Q.10 What are some of the competitive products and processes in this power module packaging market, and how big of a threat do they pose for loss of market share via material or product substitution?
- Q.11 What M & A activities did take place in the last five years in this, power module packaging market?

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